



[10191/3935]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : LAERMER ET AL.
Filed : January 05, 2005
Serial No. : 10/506,457
For : DEVICE AND METHOD FOR ANISOTROPIC
PLASMA ETCHING OF A SUBSTRATE,
A SILICON BODY IN PARTICULAR
Examiner : Allan W. Olsen
Art Unit : 1763
Confirmation No. : 9990

Address to:

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Date: August 15, 2006
Signature: Chihlini

AMENDMENT

SIR:

In response to the Office Action dated March 30, 2006 please amend the above-captioned application without prejudice as follows:

Amendments to the Drawings begin on page 2 of this paper.

Remarks begin on page 3 of this paper.

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